

MOSFET – Power, N-Channel, SUPERFET[®] II, FRFET[®]

650 V, 76 A, 41 mΩ

FCH041N65EFLN4

Description

SUPERFET II MOSFET is ON Semiconductor's brand-new high voltage super-junction (SJ) MOSFET family that is utilizing charge balance technology for outstanding low on-resistance and lower gate charge performance. This advanced technology is tailored to minimize conduction loss, provides superior switching performance, and withstand extreme dv/dt rate.

Consequently, SUPERFET II MOSFET is very suitable for the various power system for miniaturization and higher efficiency. SUPERFET II FRFET MOSFET's optimized reverse recovery performance of body diode can remove additional component and improve system reliability.

Features

- 700 V @ T_J = 150°C
- Typ. R_{DS(on)} = 36 mΩ
- Ultra Low Gate Charge (Typ. Q_g = 229 nC)
- Low Effective Output Capacitance (Typ. C_{oss(eff.)} = 631 pF)
- 100% Avalanche Tested
- These Devices are Pb-Free and are RoHS Compliant

Applications

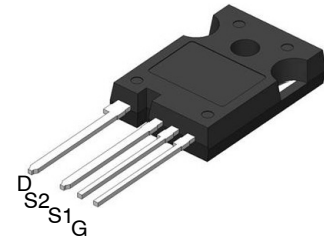
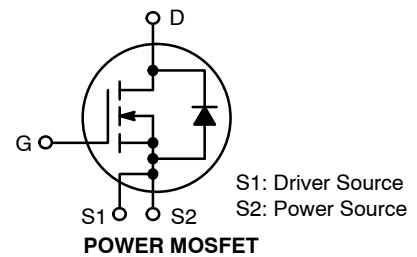
- Telecom / Server Power Supplies
- Industrial Power Supplies
- EV Charger
- UPS / Solar



ON Semiconductor[®]

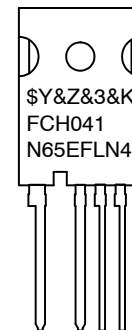
www.onsemi.com

V _{DSS}	R _{DS(ON)} MAX	I _D MAX
650 V	41 mΩ @ 10 V	76 A



TO-247-4LD
CASE 340CW

MARKING DIAGRAM



- \$Y = ON Semiconductor Logo
- &Z = Assembly Plant Code
- &3 = Data Code (Year & Week)
- &K = Lot
- FCH041N65EFLN4 = Specific Device Code

ORDERING INFORMATION

See detailed ordering and shipping information on page 2 of this data sheet.

FCH041N65EFLN4

ABSOLUTE MAXIMUM RATINGS (T_C = 25°C, Unless otherwise noted)

Symbol	Parameter	Value	Unit
V _{DSS}	Drain to Source Voltage	650	V
V _{GSS}	Gate to Source Voltage	- DC	±20
		- AC (f > 1 Hz)	±30
I _D	Drain Current	- Continuous (T _C = 25°C)	76
		- Continuous (T _C = 100°C)	48.1
I _{DM}	Drain Current	- Pulsed (Note 1)	228
E _{AS}	Single Pulsed Avalanche Energy (Note 2)	2025	mJ
I _{AS}	Avalanche Current (Note 2)	15	A
E _{AR}	Repetitive Avalanche Energy (Note 1)	5.95	mJ
dv/dt	MOSFET dv/dt	100	V/ns
	Peak Diode Recovery dv/dt (Note 3)	50	
P _D	Power Dissipation	(T _C = 25°C)	595
		- Derate Above 25°C	4.76
T _J , T _{STG}	Operating and Storage Temperature Range	-55 to +150	°C
T _L	Maximum Lead Temperature for Soldering, 1/8" from Case for 5 seconds	300	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. Repetitive rating: pulse width limited by maximum junction temperature.
2. I_{AS} = 15 A, R_G = 25 Ω, starting T_J = 25°C.
3. I_{SD} ≤ 38 A, di/dt ≤ 200 A/μs, V_{DD} ≤ 380 V, starting T_J = 25°C.

THERMAL CHARACTERISTICS

Symbol	Parameter	Value	Unit
R _{θJC}	Thermal Resistance, Junction to Case, Max.	0.21	°C/W
R _{θJA}	Thermal Resistance, Junction to Ambient, Max.	40	

PACKAGE MARKING AND ORDERING INFORMATION

Part Number	Top Marking	Package	Packing Method	Reel Size	Tape Width	Quantity
FCH041N65EFLN4	FCH041N65EFLN4	TO-247 L4 Narrow Lead	Tube	N/A	N/A	30 Units

ELECTRICAL CHARACTERISTICS (T_C = 25°C unless otherwise noted)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
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OFF CHARACTERISTICS

BV _{DSS}	Drain to Source Breakdown Voltage	V _{GS} = 0 V, I _D = 10 mA, T _J = 25°C	650	-	-	V
		V _{GS} = 0 V, I _D = 10 mA, T _J = 150°C	700	-	-	V
ΔBV _{DSS} / ΔT _J	Breakdown Voltage Temperature Coefficient	I _D = 10 mA, Referenced to 25°C	-	0.72	-	V/°C
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = 650 V, V _{GS} = 0 V	-	-	10	μA
		V _{DS} = 520 V, T _C = 125°C	-	145	-	
I _{GSS}	Gate to Body Leakage Current	V _{GS} = ±20 V, V _{DS} = 0 V	-	-	±100	nA

ON CHARACTERISTICS

V _{GS(th)}	Gate Threshold Voltage	V _{GS} = V _{DS} , I _D = 7.6 mA	3.0	-	5.0	V
R _{DS(on)}	Static Drain to Source On Resistance	V _{GS} = 10 V, I _D = 38 A	-	36	41	mΩ

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ELECTRICAL CHARACTERISTICS ($T_C = 25^\circ\text{C}$ unless otherwise noted) (continued)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
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ON CHARACTERISTICS

g_{FS}	Forward Transconductance	$V_{DS} = 20\text{ V}, I_D = 38\text{ A}$	–	71.7	–	S
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DYNAMIC CHARACTERISTICS

C_{iss}	Input Capacitance	$V_{DS} = 100\text{ V}, V_{GS} = 0\text{ V}, f = 1\text{ MHz}$	–	9446	12560	pF
C_{oss}	Output Capacitance		–	366	490	pF
C_{rss}	Reverse Transfer Capacitance		–	35	–	pF
C_{oss}	Output Capacitance	$V_{DS} = 380\text{ V}, V_{GS} = 0\text{ V}, f = 1\text{ MHz}$	–	197	–	pF
$C_{oss(eff.)}$	Effective Output Capacitance	$V_{DS} = 0\text{ V to } 400\text{ V}, V_{GS} = 0\text{ V}$	–	631	–	pF
$Q_{g(tot)}$	Total Gate Charge at 10 V	$V_{DS} = 380\text{ V}, I_D = 38\text{ A}, V_{GS} = 10\text{ V}$ (Note 4)	–	229	298	nC
Q_{gs}	Gate to Source Gate Charge		–	50	–	nC
Q_{gd}	Gate to Drain “Miller” Charge		–	90	–	nC
ESR	Equivalent Series Resistance	$f = 1\text{ MHz}$	–	0.6	–	Ω

SWITCHING CHARACTERISTICS

$t_{d(on)}$	Turn-On Delay Time	$V_{DD} = 380\text{ V}, I_D = 38\text{ A},$ $V_{GS} = 10\text{ V}, R_g = 2\ \Omega$ (Note 4)	–	55	120	ns
t_r	Turn-On Rise Time		–	25	60	ns
$t_{d(off)}$	Turn-Off Delay Time		–	169	348	ns
t_f	Turn-Off Fall Time		–	18	46	ns

SOURCE-DRAIN DIODE CHARACTERISTICS

I_S	Maximum Continuous Drain to Source Diode Forward Current	–	–	76	A	
I_{SM}	Maximum Pulsed Drain to Source Diode Forward Current	–	–	228	A	
V_{SD}	Drain to Source Diode Forward Voltage	$V_{GS} = 0\text{ V}, I_{SD} = 38\text{ A}$	–	–	1.2	V
t_{rr}	Reverse Recovery Time	$V_{GS} = 0\text{ V}, I_{SD} = 38\text{ A},$ $dI_F/dt = 100\text{ A}/\mu\text{s}$	–	207	–	ns
Q_{rr}	Reverse Recovery Charge		–	1.5	–	μC

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

4. Essentially independent of operating temperature typical characteristics.

TYPICAL PERFORMANCE CHARACTERISTICS

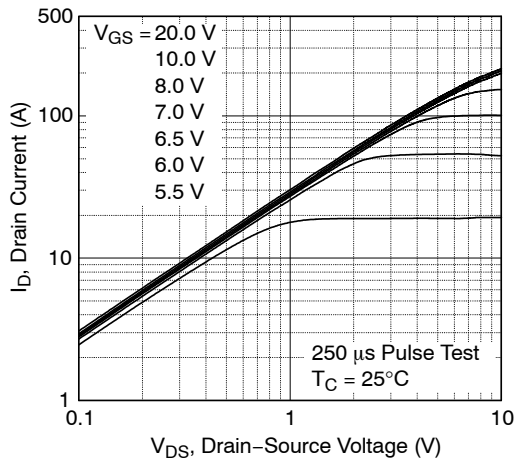


Figure 1. On-Region Characteristics

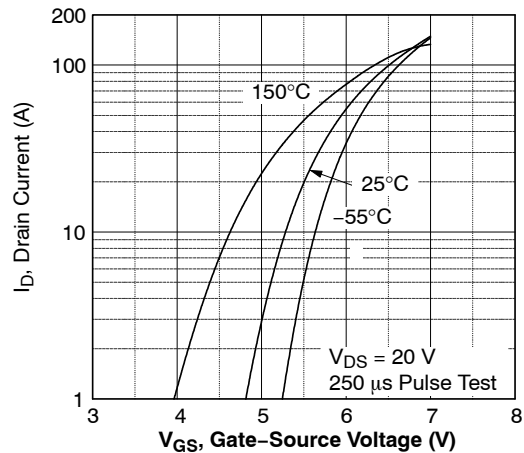


Figure 2. Transfer Characteristics

TYPICAL PERFORMANCE CHARACTERISTICS (continued)

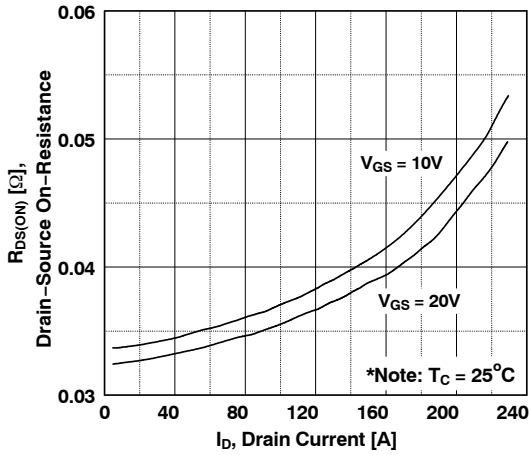


Figure 3. On-Resistance Variation vs. Drain Current and Gate Voltage

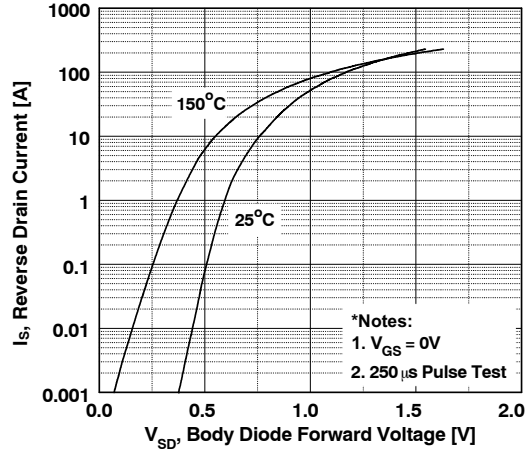


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

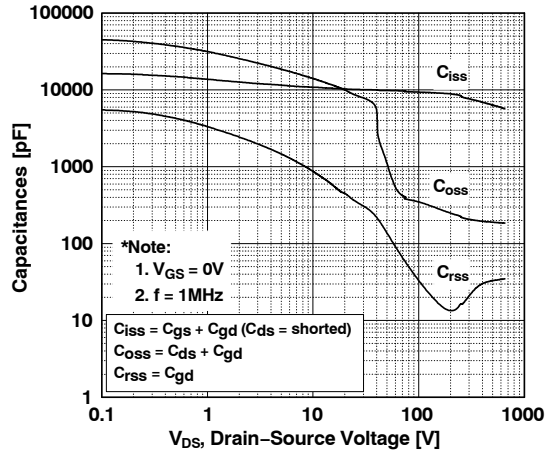


Figure 5. Capacitance Characteristics

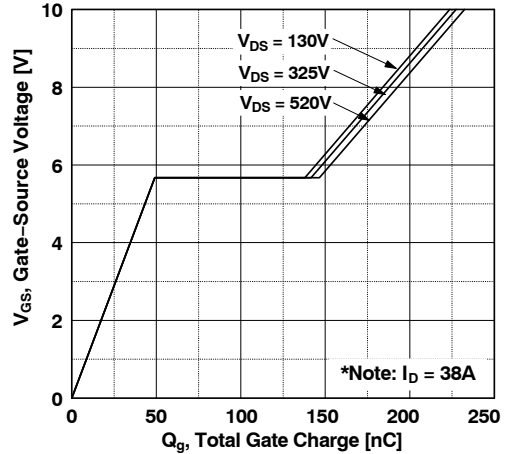


Figure 6. Gate Charge Characteristics

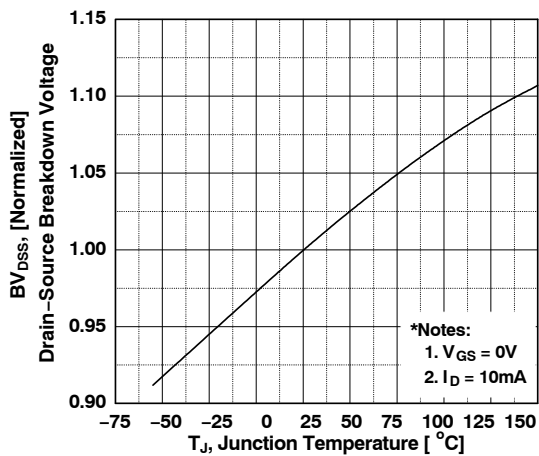


Figure 7. Breakdown Voltage Variation vs. Temperature

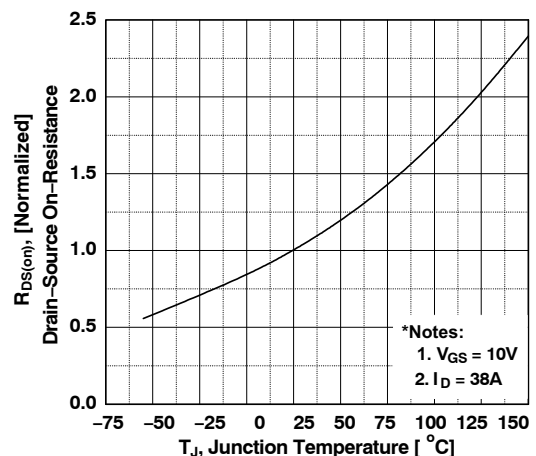


Figure 8. On-Resistance Variation vs. Temperature

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TYPICAL PERFORMANCE CHARACTERISTICS (continued)

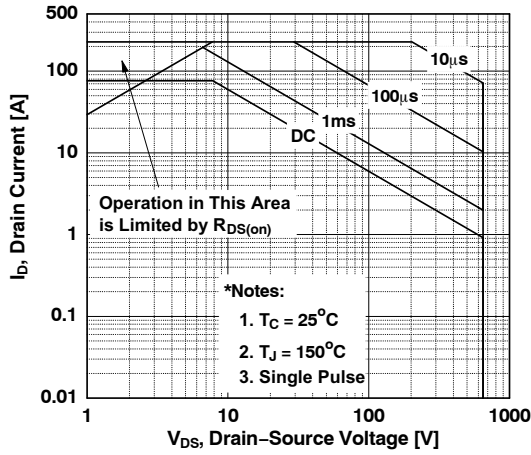


Figure 9. Maximum Safe Operating Area

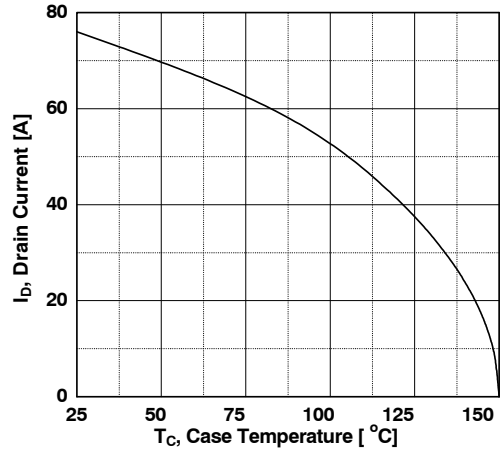


Figure 10. Maximum Drain Current vs. Case Temperature

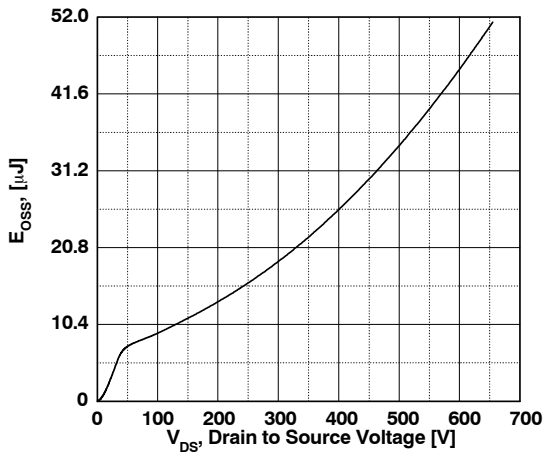


Figure 11. E_{OSS} vs. Drain to Source Voltage

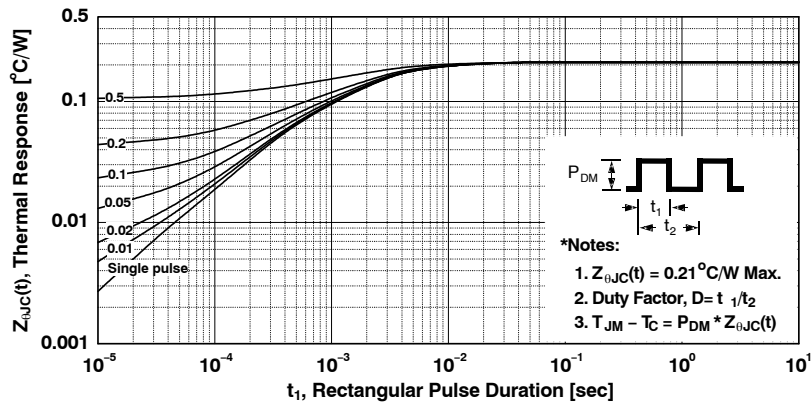


Figure 12. Transient Thermal Response Curve

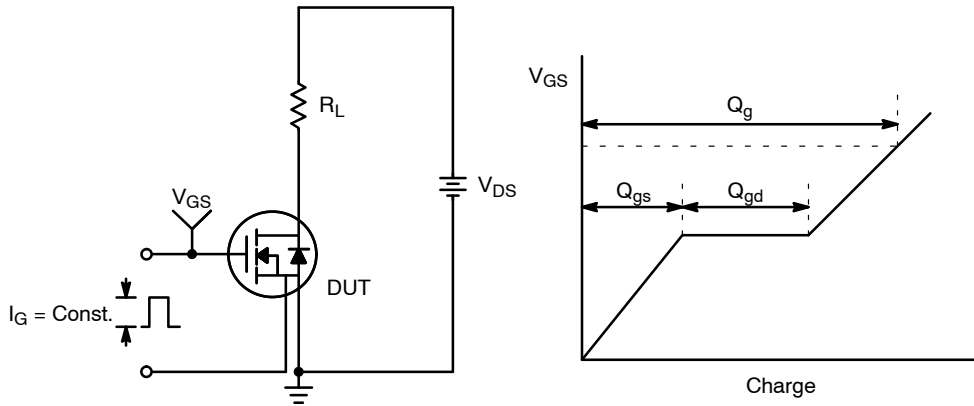


Figure 13. Gate Charge Test Circuit & Waveform

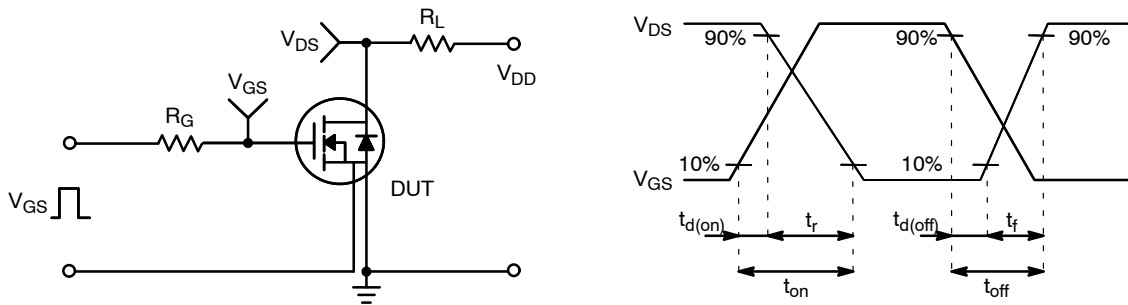


Figure 14. Resistive Switching Test Circuit & Waveforms

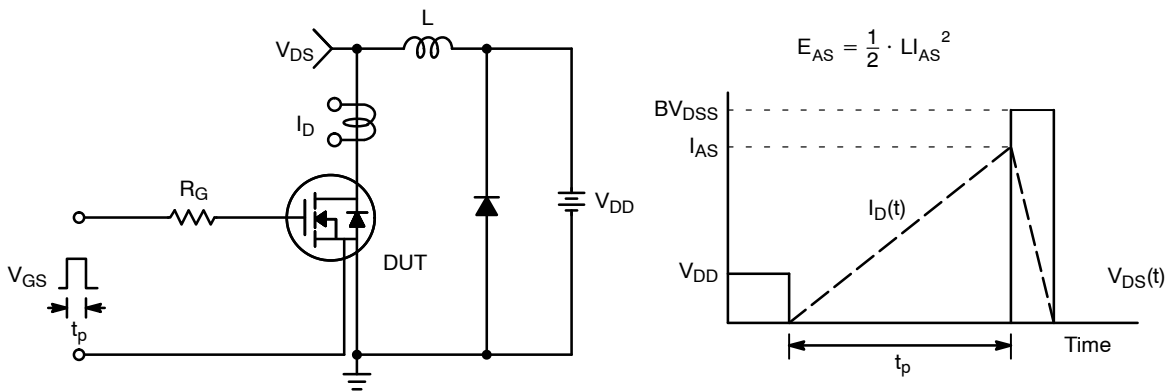


Figure 15. Unclamped Inductive Switching Test Circuit & Waveforms

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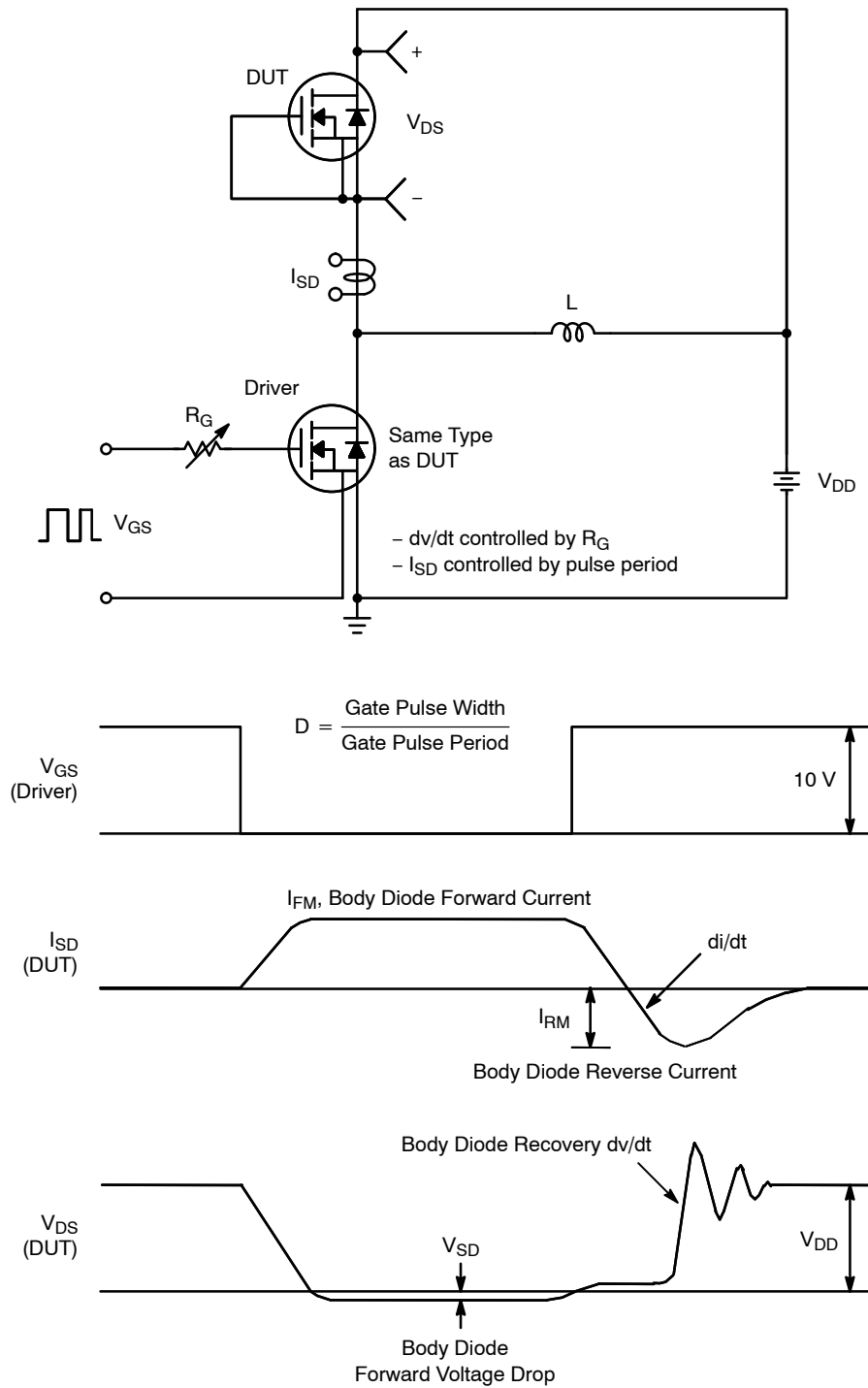
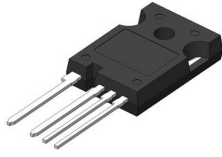


Figure 16. Peak Diode Recovery dv/dt Test Circuit & Waveforms

MECHANICAL CASE OUTLINE

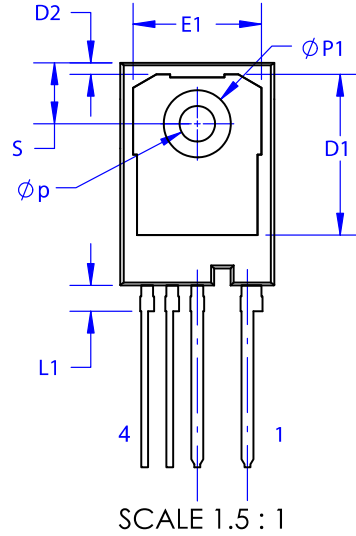
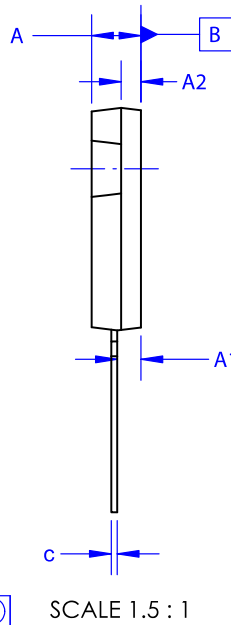
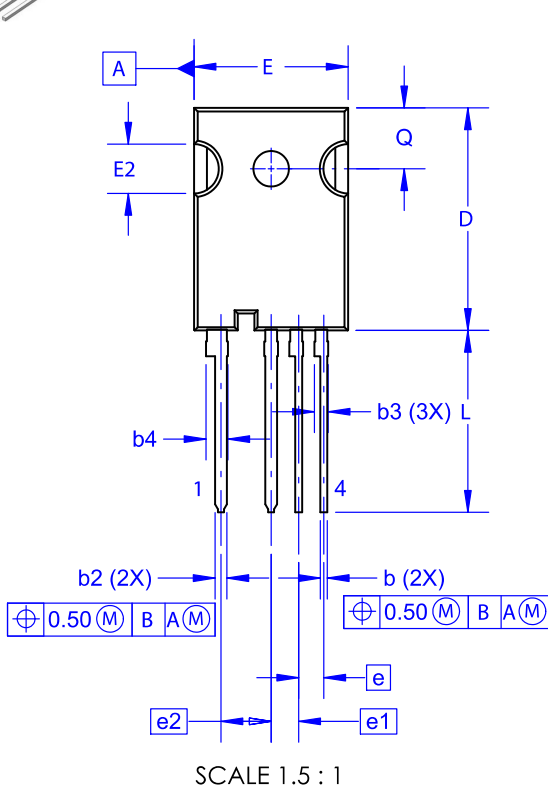
PACKAGE DIMENSIONS

ON Semiconductor®



TO-247 4-LEAD, THIN LEADS CASE 340CW ISSUE A

DATE 16 SEP 2019



DIM	MILLIMETERS		
	MIN	NOM	MAX
A	4.80	5.00	5.20
A1	2.10	2.40	2.70
A2	1.80	2.00	2.20
b	0.57	0.70	0.83
b2	1.07	1.20	1.33
b3	1.20	1.40	1.60
b4	2.02	2.22	2.42
c	0.50	0.60	0.70
D	22.34	22.54	22.74
D1	16.00	16.30	16.50
D2	0.97	1.17	1.37
e		2.54	
e1		2.79	
e2		5.08	
E	15.40	15.60	15.80
E1	12.80	13.00	13.20
E2	4.80	5.00	5.20
L	18.12	18.42	18.72
L1	2.42	2.62	2.82
Øp	3.40	3.60	3.80
ØP1	6.60	6.80	7.00
Q	5.97	6.17	6.37
S	5.97	6.17	6.37

NOTES:

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